

We claim:

1. A digital camera, comprising:
 - an image sensor module, comprising a camera lens with a non-spherical surface and an image sensor for transforming optical signals to analog signals, wherein the camera lens is spaced apart from the image sensor;
 - a Digital Signal Processor (DSP) for transforming analog signals to digital signals;
 - a Microprogrammed Control Unit (MCU) for processing the digital signals out from the DSP;
 - a dynamic random access memory (DRAM) for storing data;
 - an output apparatus; and
 - a circuitry for connecting the image sensor module, the DSP, the MCU, the DRAM and the output apparatus together.
2. The digital camera as claimed in claim 1, wherein the image sensor further includes an infrared septum.
3. The digital camera as claimed in claim 2, wherein the camera lens further includes a lens part.
4. The digital camera as claimed in claim 2, wherein the camera lens further includes a mounting part.
5. The digital camera as claimed in claim 4, wherein the infrared septum is plating on a face of the mounting part.
6. The digital camera as claimed in claim 1, wherein the image sensor further includes several sensitization elements and an underlay.

7. The digital camera as claimed in claim 1, wherein the camera lens is fixed to the image sensor by hot mold glue.

8. The digital camera as claimed in claim 7, wherein the hot mold glue is 353ND epoxy.

9. A digital camera, comprising:

an image sensor module, comprising a camera lens with a non-spherical surface and an image sensor for transforming optical signals to analog signals, wherein the camera lens is spatially fastened to the image sensor;

a Digital Signal Processor (DSP) for transforming analog signals to digital signals;

a Microprogrammed Control Unit (MCU) for processing the digital signals out from the DSP;

a dynamic random access memory (DRAM) for storing data;

an output apparatus; and

a circuitry for connecting the image sensor module, the DSP, the MCU, the DRAM and the output apparatus together.

10. A method of capturing a picture, comprising:

providing a an image sensor module with a camera lens, which defines a non-spherical surface, and an image sensor for transforming optical signals to analog signals, wherein the camera lens is spatially fastened to the image sensor; and

coating an infrared layer upon a back surface of said lens and between said lens and said image sensor.